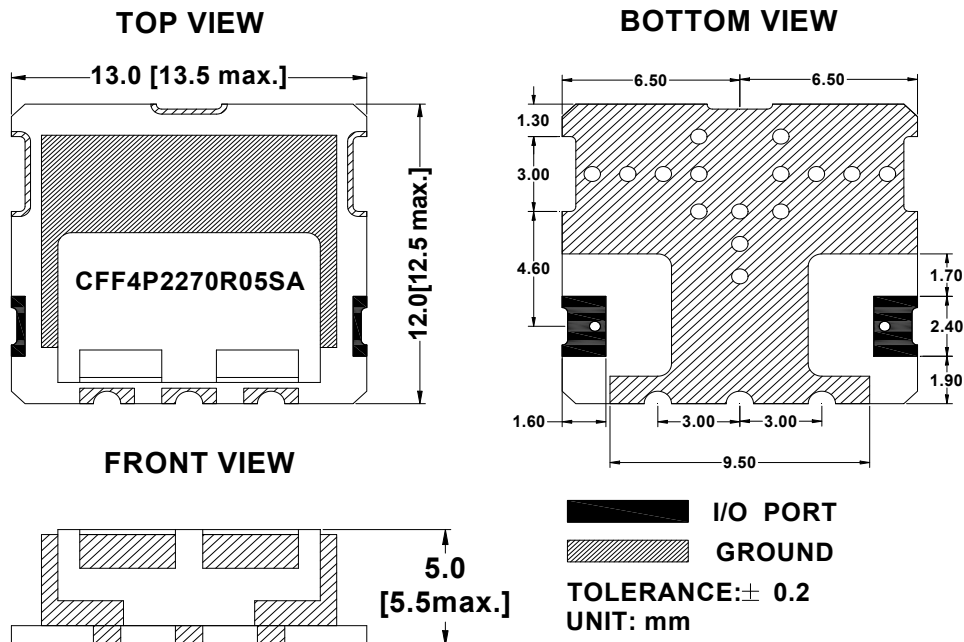


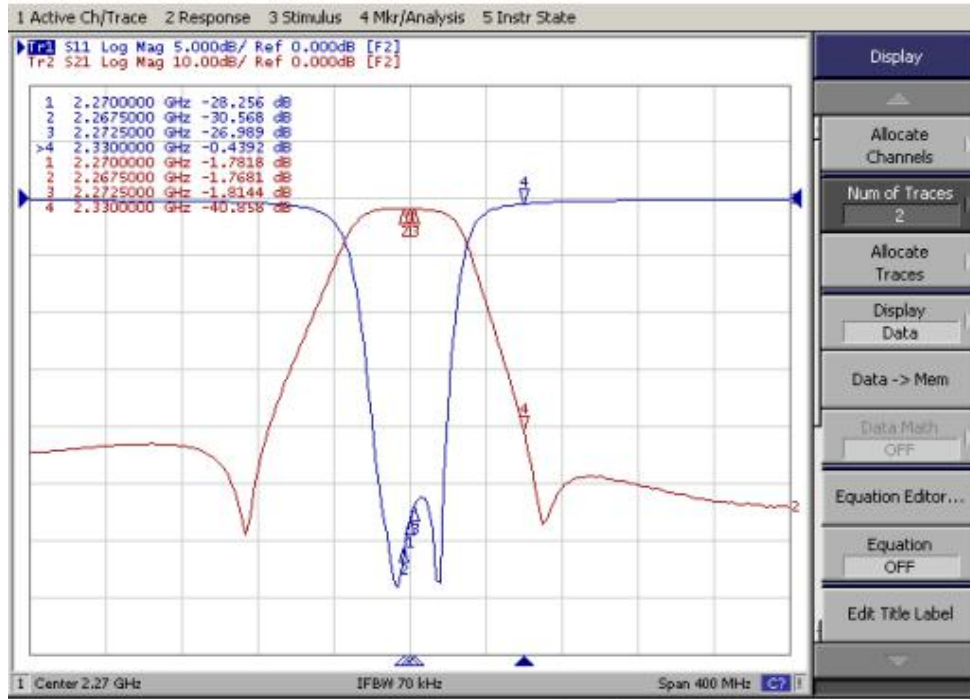
**Electrical Specification**

ITEMS	SPEC	UNIT
Center Frequency [fo]	2270.0	MHz
Bandwidth [BW]	$f_o \pm 2.5$ [2267.5~2272.5]	MHz
Insertion Loss in BW	2.0	dB max
Ripple in BW	0.4	dB max
Return Loss in BW	15.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	60dB min. @ $f_o \pm 80.0$ [ 125 ~ ]	MHz
	40dB min. @ $f_o \pm$ [ 2330 ~ ]	MHz
	dB min. @ $f_o \pm$ [ ~ ]	MHz
	dB min. @ $f_o \pm$ [ & ]	MHz
Group Delay Variation		ns max
Input Power		W max.
In/Out Impedance	50 $\Omega$	
Operation Temperature Range	-40°C to +85°C	

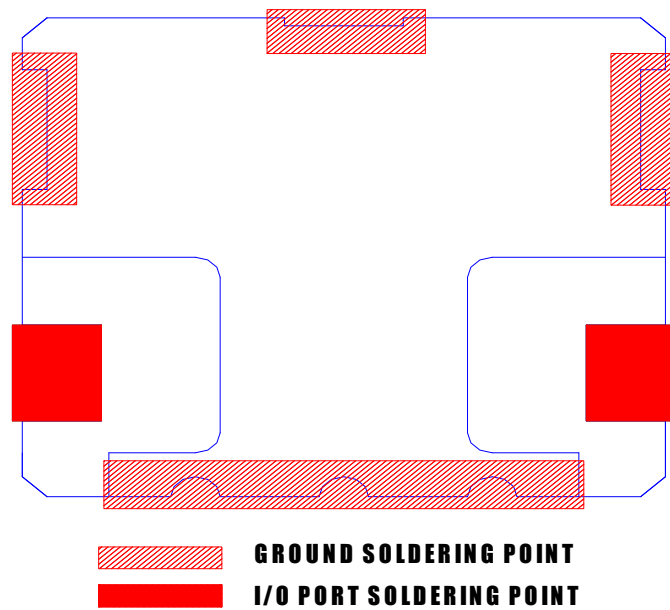
**Mechanical Specification**



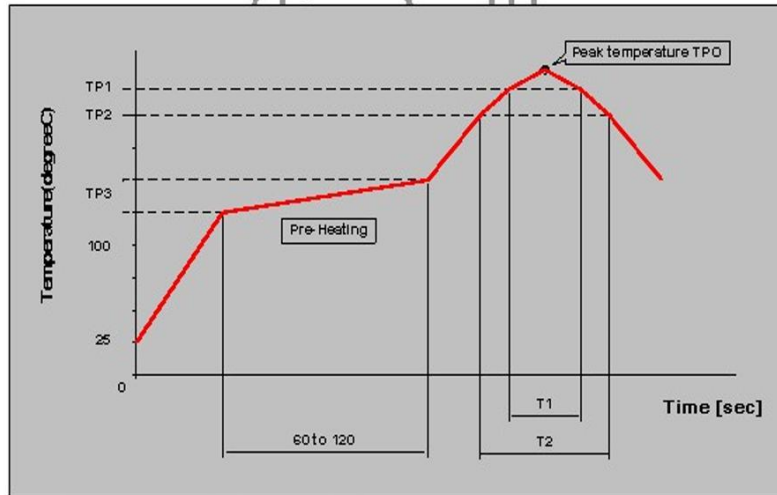
## Plot Data



## Recommended PC Board Pattern



**Soldering Condition**



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180